Taiwan: Enabling the Next Generation Semiconductor Industry

Taiwan, with its globally unique full-established and highly specialized supply chains along with its horizontal integration capabilities, will benefit from the increasing market demands of semiconductor devices. Taiwan's global leadership in chip design, foundry, and package and test services has not only contributed to its long-term growth in economy but also facilitated international collaboration and technology innovation in the semiconductor sector.

Ramping up for 5 nm and beyond, new techniques, such as heterogeneous integration and novel materials are introduced to maintain the efficiency of semiconductor processes. However, what really concerns corporate managements today is to develop market-oriented, flexible, and high-quality manufacturing technologies and eventually create business models with differentiated values by integrating user-experiences. We can help you find the answers!

SEMICON Taiwan: Connect, Collaborate, and Innovate

High performance computing that has broadly adopted in mobile and mobile devices, multifunctional mobile products with shortened life cycles, safer, smarter, and more environmentally friendly automobiles, Internet of Things, and Artificial Intelligences are all the next growth engines for the semiconductor industry. SEMICON Taiwan, serving as the ideal platform for connection, collaboration, and innovation, will continue assisting companies in the global semiconductor ecosystem to establish concrete foundations and create irreplaceable values in those new application markets.

Meet more potential customers at SEMICON Taiwan 2019

SEMICON Taiwan gives you more ways to reach and engage your customers and prospects from your booth and beyond, including:

• Supplier Search Program: Engage with the world’s leading semiconductor manufacturers, including UMC, Micron, SONY and more.
• More than 22 International Programs: A full agenda of technical and business sessions, annually attracting more than 6,000 attendees to attend.
• TechXPOT: An exhibitor exclusive speaking opportunity that provides an ideal platform for new product launches.
• Networking Events: Leadership Gala Dinner gathers more than 600 industry elites and executive management from TSMC, UMC, ASE, Powerchip, SPIL, MediaTek, Amkor, Micron, and other industry-leading companies.
• Diverse Marketing and Sponsorship Opportunities: Promote your company through integrated marketing promotion tools and opportunities.

The Most Comprehensive Cross-Industry Platform

• SMART Manufacturing Expo: Focused on the solutions and best practices of smart manufacturing in high-tech industries.
• SMART Transportation Summit: Focused on connectivity, autonomous driving, and electric vehicles to facilitate the future mobility.
• ESD Alliance Summit: Connect IC design, foundry, EDA and IP to shape the next generation chip design technology.
SEMICON Taiwan Visitor Profile

As the premier electronics manufacturing supply chain event in Taiwan, SEMICON Taiwan is the best platform to connect buyers, engineers, key influencers, and decision-makers involved in the equipment, materials, and services buying cycle. Among SEMICON Taiwan visitors, 54% are manager level or above, and 59% influence purchasing decisions.

Areas of Interest

APPLICATIONS
- SMART Manufacturing: 41%
- Automotive Electronics/SMART Transportation: 21%
- Artificial Intelligence Systems (AI): 20%
- Internet of Things (IoT): 18%
- Mobile Technologies/Wireless/5G: 14%
- OLED: 13%
- Virtual Reality/Augmented Reality (VR/AR): 13%
- Consumer Electronics: 11%
- Wearables: 10%
- Laser Processing Application: 9%
- Power Device/Power Systems: 9%
- Medical Electronics/MedTech: 8%
- Green Manufacturing/EHS: 7%
- Imaging: 7%
- Cloud Computing/High-Performance Computing: 5%
- Other Applications: 21%

Areas of Interest

DESIGN/MANUFACTURING SERVICES
- Packaging and Test Services (OSAT): 22%
- Design/EDA: 19%
- Engineering Services: 19%
- R&D/Technology Transfer: 19%
- Manufacturing Services and Consulting: 17%
- Foundries: 16%
- Electronic Manufacturing Services (EMS)/System Integration: 14%
- Fabless: 11%
- Factory Control/Process Software: 10%
- Other Design/Manufacturing Services: 10%
- Other Manufacturing Equipment: 19%

MANUFACTURING EQUIPMENT
- Front-end Processing: 22%
- Assembly/Packaging: 20%
- Test: 19%
- Factory Automation/Robotics: 11%
- Inspection and Measurement/Metrology I: 1%
- Parts: 10%
- Large-area/Thin Film: 8%
- Printing/Coating/Roll-to-Roll: 8%
- Secondary Equipment and Services: 6%
- Components/Sub-systems/Instrumentation: 5%
- Laser Systems for Production Engineering: 3%
- Abatement/Environmental Systems: 3%
- Circular Economy/Recycling/Waste Management: 3%
- Other Manufacturing Equipment: 19%

MATERIALS
- Wafers/Substrates: 30%
- Packaging/Assembly: 20%
- Process Materials: Gases/Liquids/Solids/Chemicals: 19%
- Cleaning: 13%
- Compound Semiconductor/Power Device: 12%
- LED/MEMS/Sensors/PV/Display Manufacturing: 12%
- Consumables: 9%
- Inks/Pastes/Printing Materials: 7%
- Other Materials: 16%

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*Partial list and data; see the SEMICON Taiwan 2017 Post-show Report online at www.semicontaiwan.org for additional data and information.

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